LCD trimming system

- Variable trimming line width (IR/Green)
- Field proven quality and high productivity
- User friendly software

TSP patterning system

- ITO / Ag / AgNW / Graphene patterning
- Multi-head patterning
- High-speed, high-accuracy beam control
Glass drilling & cutting system

- Short pulse laser (Minimum thermal damage)
- Vision based scanner calibration
- High speed & positioning accuracy

<table>
<thead>
<tr>
<th>Gorilla glass</th>
<th>Sapphire</th>
</tr>
</thead>
<tbody>
<tr>
<td>![Image of Gorilla glass]</td>
<td>![Image of Sapphire]</td>
</tr>
<tr>
<td>3.02μm</td>
<td>5.55μm</td>
</tr>
<tr>
<td>5.0μm</td>
<td>5.0μm</td>
</tr>
</tbody>
</table>

Ra < 0.50μm Ra < 0.25μm
Business Area

Semiconductor

Display

PCB

Macro

- LCD trimming system
- TSP patterning system
- Glass drilling & cutting system
- OLED PI film cutting system
- FPD (LCD/OLED) marking system
- GLA (Green laser annealing)
- LLO (Laser lift-off)

OLED PI film cutting system

- Flexible OLED film cutting inline/offline
- Full, half and chamfering cutting processes
- Multi-head cutting system

FPD (LCD/OLED) marking system

- LCD/OLED marking (Metal / PR layer)
- Automated focusing control
- AGC (Automated Grid Calibration)
GLA (Green laser annealing)

- High quality Poly-Si annealing with DPSS laser
- Full or partial melt annealing for AMOLED and TFT-LCD
- Developed by world class line beam optics technology
- Low cost of ownership

LLO (Laser lift-off)

- High power UV wavelength for material processing
- Reliable DPSS laser operation
- Wide area processing with high power DPSS laser